

Rev.I.Feb.-2019

SOD-123

Schottky Diode in a SOD-123 Plastic Package.

Low positive pressure drop. HF Product.

Schottky diode.



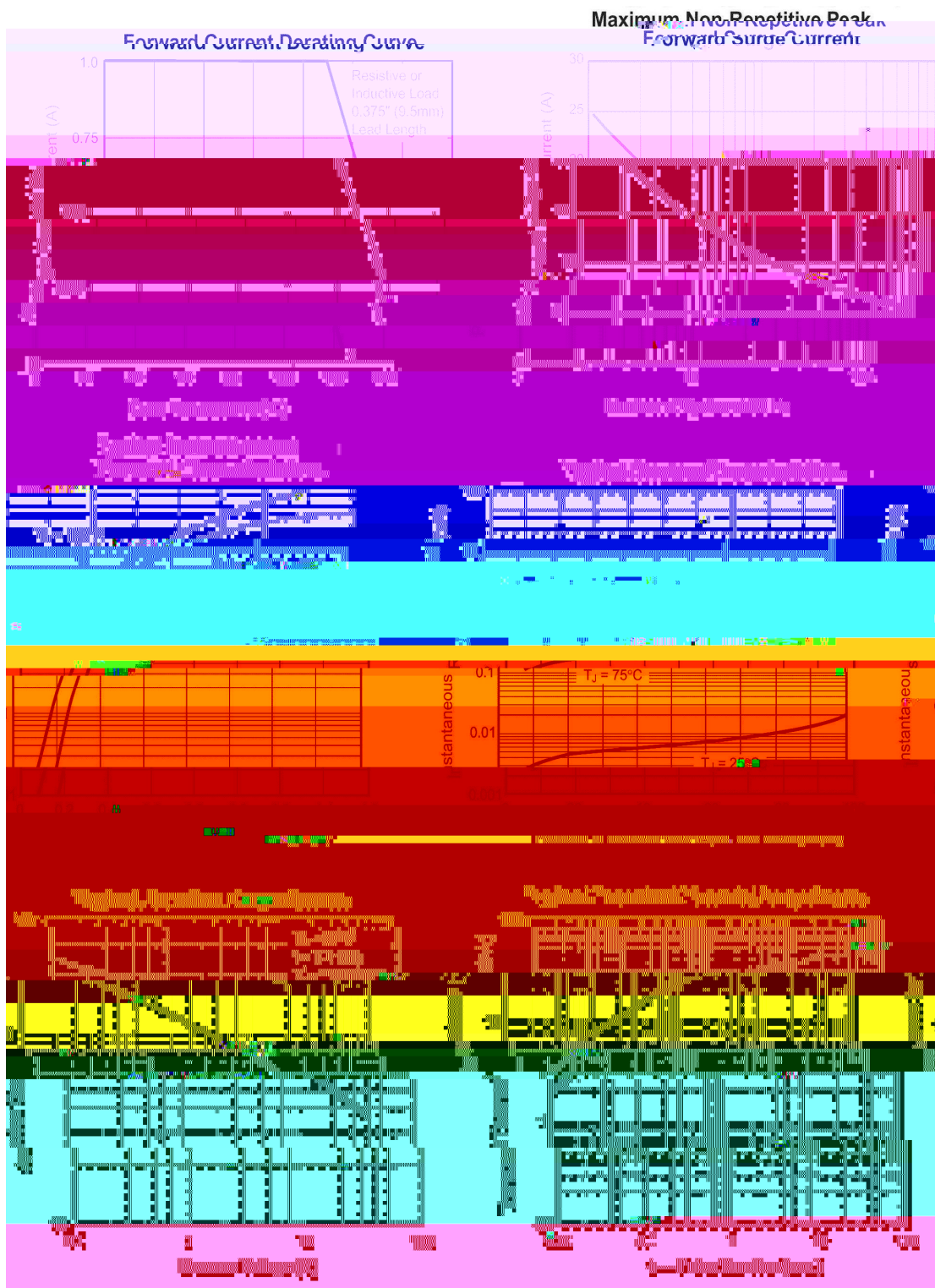
PIN1:Cathode

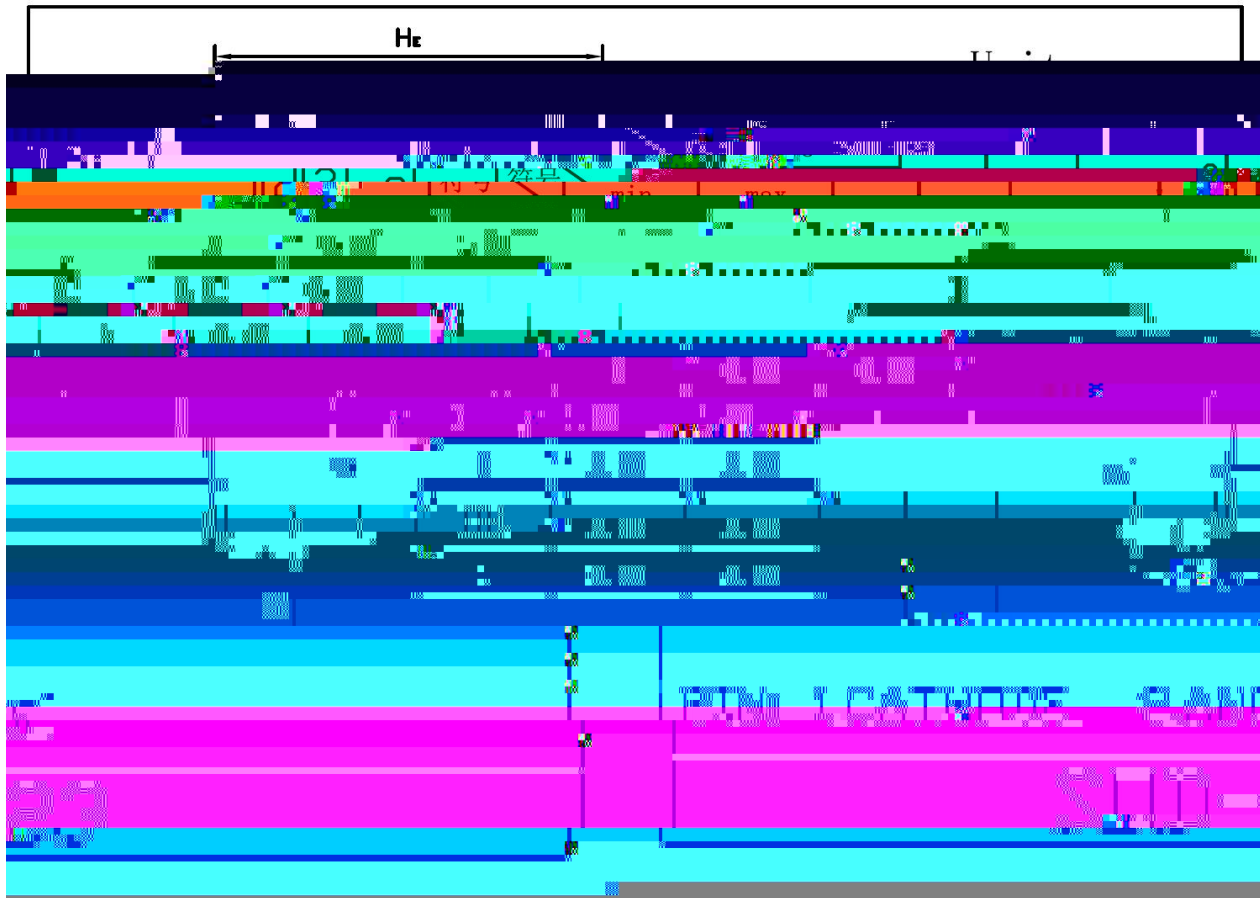
PIN2:Anode

Model	B5817W	B5818W	B5819W
Marking	HSJ	HSK	HSL

Parameter	Symbol	Rating			Unit
		B5817W	B5818W	B5819W	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Reverse Voltage	V_{RRM} V_{RWM} V_R	20	30	40	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	V
Average Rectified Forward Current	I_F	1			A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	25			A
Power Dissipation	P_D	450			mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	220			°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	-65 to 125			°C

Parameter	Symbol	Test Conditions	Rating						Unit
			B5817W		B5818W		B5819W		
			MIN	MAX	MIN	MAX	MIN	MAX	
Reverse breakdown voltage	V _(BR)	I _R =1mA	20		30		40		V
Forward Voltage	V _F	I _F =0.1A		0.32		0.35		0.40	V
		I _F =1A		0.45		0.55		0.60	
		I _F =3A (t<5us)		0.75		0.875		0.90	
Instantaneous Reverse Current	I _{RM}	V _R =V _{RRM}	1						mA
Junction Capacitance	C _J	V _R =4V f=1.0MHZ	120						pF







H

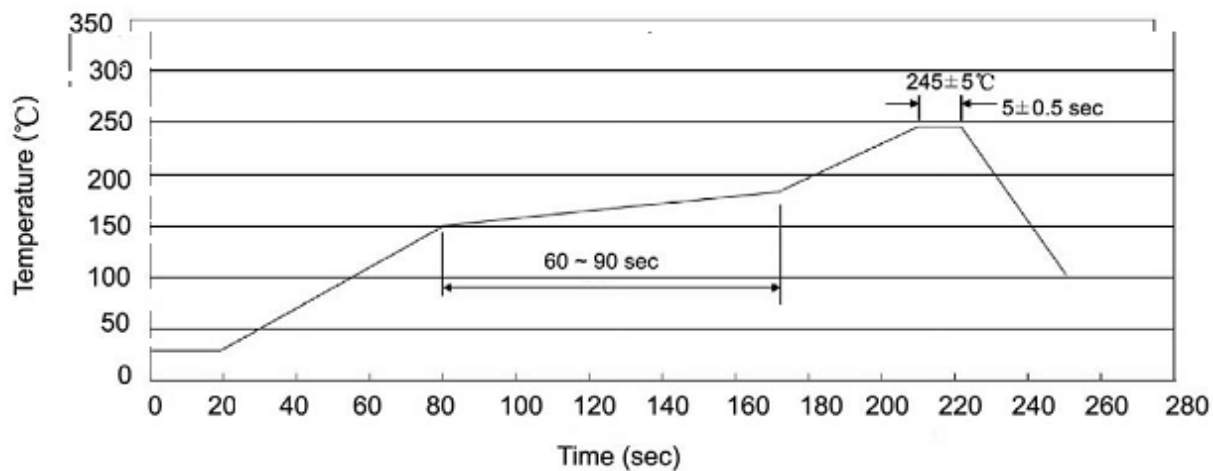
SJ

Note:

H: Company Code.

SJ: Product Type.

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

260±5

10±1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205